

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
C-1	SILK SCREEN CHANGES -REMOVED MBARI LOGO -INPUT VOLTAGE MAX CHANGED TO 16V	02/06	APPROVED

CLASS II FABRICATION NOTES: (UNLESS OTHERWISE SPECIFIED)

1. BOARDS SHALL BE 100% NET LIST TESTED FOR OPENS AND SHORTS PER PROVIDED IPC-D-356 NETLIST.
2. THIS BOARD SHALL BE MANUFACTURED IN ACCORDANCE WITH IPC-6012A CLASS II SPECIFICATIONS AND MEET IPC-600 CLASS II ACCEPTABILITY STANDARDS.
3. MATERIAL:

a. FR4 PER IPC 4101B/24 /26 , OR /28.

b. SIGNAL LAYERS TO BE 2 OZ. COPPER.

c. ~~PLANE LAYERS TO BE 1 OZ. COPPER.~~

d. OVERALL THICKNESS TO BE 0.062" +/- 10%
4. LEGEND:

a. WHITE NON-CONDUCTIVE EPOXY INK BOTH SIDES.
5. SOLDERMASK:

a. APPLY LIQUID PHOTO-IMAGABLE (LPI) SOLDER MASK OVER BARE COPPER PER IPC-SM-840 CLASS H, COLOR MATTE BLUE, BOTH SIDES.
6. PLATING FINISH:

a. HOT AIR SOLDER LEVELING (HASL) SN63A SnPb SOLDER.

b. ~~IMMERSION SILVER TAG.~~
7. PROCESS ALLOWANCES:

a. MAXIMUM BOW AND TWIST ACROSS DIAGONAL CORNERS OF THE BOARD SHALL NOT EXCEED 0.75%.

b. HOLE DIMENSIONS APPLY AFTER PLATING.

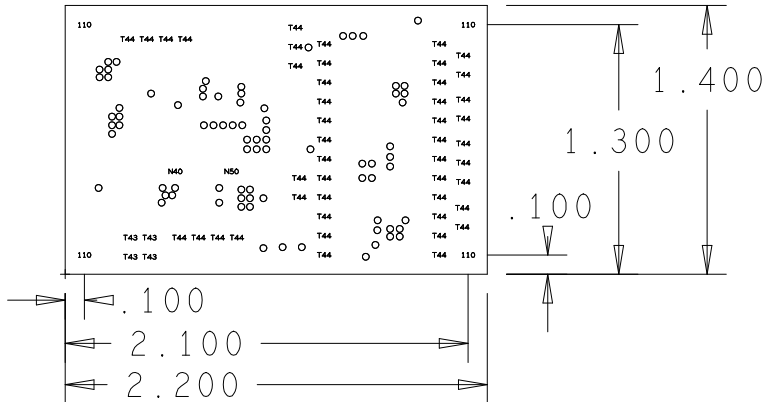
c. ALL HOLES SHALL BE LOCATED WITHIN 0.003" DIAMETER OF TRUE POSITION.

d. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003".

e. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- 0.002".

f. REMOVE ALL BURRS AND BREAK SHARP EDGES 0/015" MAX.

g. CUT OUTSIDE OF 0.001" BOARD OUTLINE.



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
o	10.0	PLATED	80
T43	43.0	PLATED	4
T44	44.0	PLATED	46
110	110.0	PLATED	4
N40	40.0	NON-PLATED	1
N50	50.0	NON-PLATED	1

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	SEESTAR PRO MINI CONTROLLER BOARD			
DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS +/- 0.02" 3 PL DECIMALS +/- 0.005" ANGLES +/- 1 Degree FRACTIONS +			MONTEREY BAY AQUARIUM RESEARCH INSTITUTE 7700 SANDHOLDT ROAD MOSS LANDING, CA			
			SIZE	REVISION	DWG NO	
			B	C-1	10021167	
	DESIGNED BY: CHAD KEYC		SCALE		SHEET	
	LAYOUT BY: AMY CHEN		1 - 1		1 - 1	